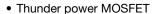
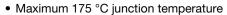


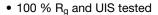
VBM1105 Datasheet N-Channel 100 V (D-S) MOSFET

| PRODUCT SUMMARY | | | | |
|---|--------|--|--|--|
| V _{DS} (V) | 100 | | | |
| $R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$ | 0. 005 | | | |
| I _D (A) ^a | 120 | | | |
| Configuration | Single | | | |

FEATURES



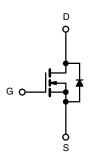




• Material categorization: for definitions of compliance please see







N-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted) | | | | | |
|--|-------------------------|-----------------------------------|------------------|---------------------------------------|--|
| PARAMETER | SYMBOL | LIMIT | UNIT | | |
| Drain-Source Voltage | V_{DS} | 100 | V | | |
| Gate-Source Voltage | V_{GS} | ± 20 | V | | |
| Continuous Proin Current (T. – 150 °C) | T _C = 25 °C | | 120 ^d | | |
| Continuous Drain Current (T _J = 150 °C) | T _C = 70 °C | - I _D | 90 d | | |
| Pulsed Drain Current (t = 100 μs) | I _{DM} | 480 | _ A | | |
| Avalanche Current | I _{AS} | 73 | | | |
| Single Avalanche Energy ^a | L = 0.1 mH | E _{AS} | 266 | mJ | |
| Maximum Power Dissipation ^a | T _C = 25 °C | D- | 370 b | W | |
| | T _C = 125 °C | P _D | 120 ^b | \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ | |
| Operating Junction and Storage Temperature Range | | T _J , T _{stg} | -55 to +175 | °C | |

| THERMAL RESISTANCE RATINGS | | | | | | |
|--|-------------------|-------|------|--|--|--|
| PARAMETER | SYMBOL | LIMIT | UNIT | | | |
| Junction-to-Ambient (PCB Mount) ^c | R _{thJA} | 40 | °C/W | | | |
| Junction-to-Case (Drain) | R_{thJC} | 0.4 | | | | |

Notes

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR4 material).
- d. Package limited.



| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNIT | |
|---|---------------------|---|------|-------|-------|----------|--|
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$ | 100 | - | - | - 4 V | |
| Gate Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_D = 250 \mu A$ | 2.5 | - | 4 | | |
| Gate-Body Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$ | - | - | ± 250 | nA | |
| | | V _{DS} = 100 V, V _{GS} = 0 V | - | - | 1 | μА | |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = 100 V, V _{GS} = 0 V, T _J = 125 °C | - | - | 150 | | |
| | | V _{DS} = 100 V, V _{GS} = 0 V, T _J = 175 °C | - | - | 5 | mA | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$ | 120 | - | - | Α | |
| Dunin Course On Chata Basistana 2 | D | V _{GS} = 10 V, I _D = 20 A | - | 0.005 | - | Ω | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | V _{GS} = 7.5 V, I _D = 15 A | - | 0.006 | - | | |
| Forward Transconductance ^a | 9 _{fs} | V _{DS} = 15 V, I _D = 20 A | - | 82 | - | S | |
| Dynamic ^b | | | | | | | |
| Input Capacitance | C _{iss} | | - | 10000 | - | pF | |
| Output Capacitance | C _{oss} | V _{GS} = 0 V, V _{DS} = 50 V, f = 1 MHz | - | 2025 | - | | |
| Reverse Transfer Capacitance | C _{rss} | | - | 165 | - | | |
| Total Gate Charge ^c | Qg | | - | 76 | 120 | | |
| Gate-Source Charge ^c | Q_{gs} | $V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$ | - | 23 | - | nC | |
| Gate-Drain Charge ^c | Q _{gd} | | - | 17 | - | | |
| Gate Resistance | R_g | f = 1 MHz | 0.6 | 3.3 | 6.6 | Ω | |
| Turn-On Delay Time ^c | t _{d(on)} | | - | 15 | 30 | | |
| Rise Time ^c | t _r | $V_{DD} = 50 \text{ V}, R_{L} = 5 \Omega$ | - | 22 | 40 | | |
| Turn-Off Delay Time ^c | t _{d(off)} | $I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$ | - | 55 | 100 | ns | |
| Fall Time ° | t _f | | - | 15 | 30 | | |
| Drain-Source Body Diode Ratings ar | nd Characteri | stics ^b (T _C = 25 °C) | | | | | |
| Pulsed Current | I _{SM} | | - | - | 480 | Α | |
| Forward Voltage ^a | V_{SD} | I _F = 10 A, V _{GS} = 0 V | - | 0.8 | 1.5 | V | |

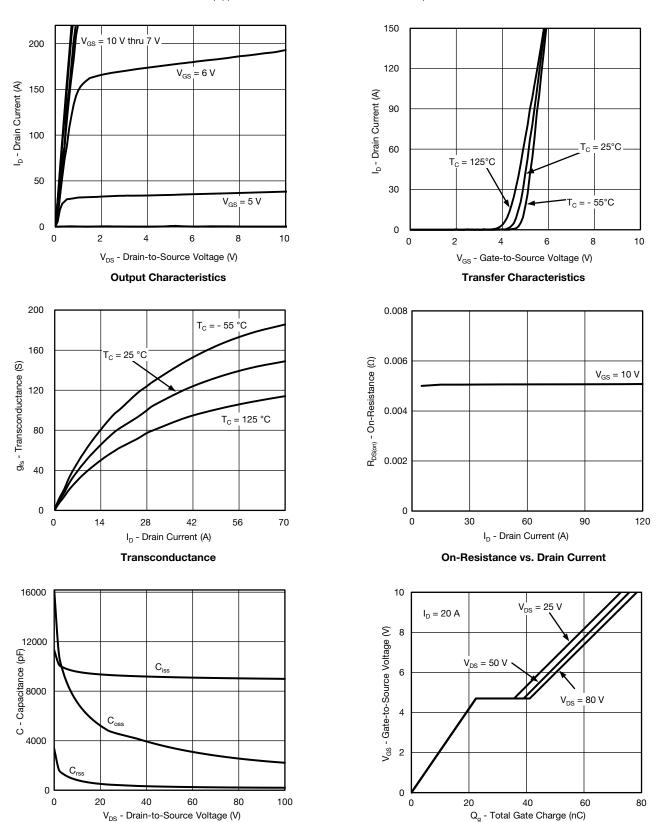
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



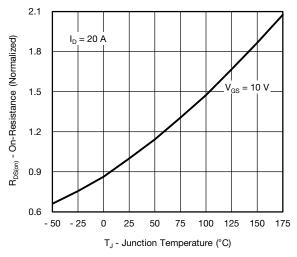
服务热线:400-655-8788

 V_{DS} - Drain-to-Source Voltage (V) $\label{eq:capacitance}$

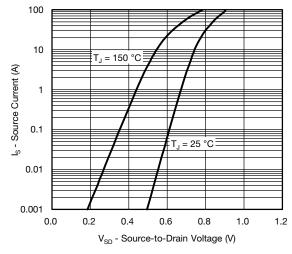
Gate Charge



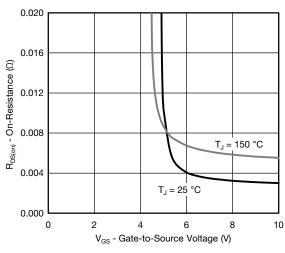
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



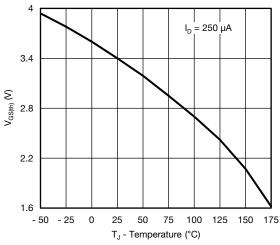
On-Resistance vs. Junction Temperature



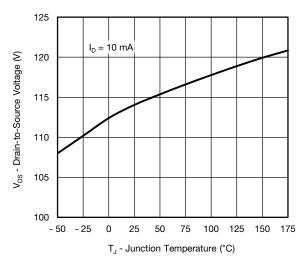
Source Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



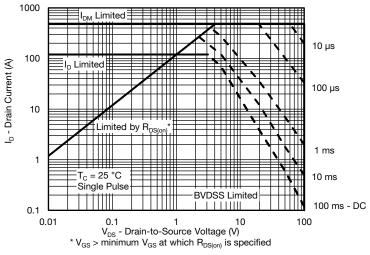
Threshold Voltage



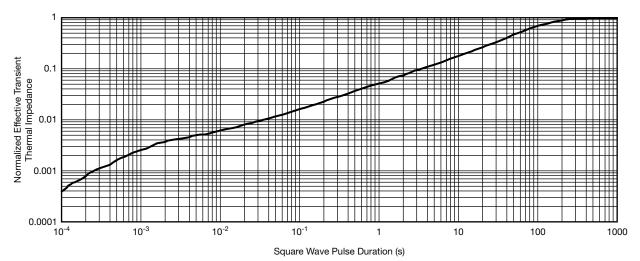
Drain Source Breakdown vs. Junction Temperature



THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)



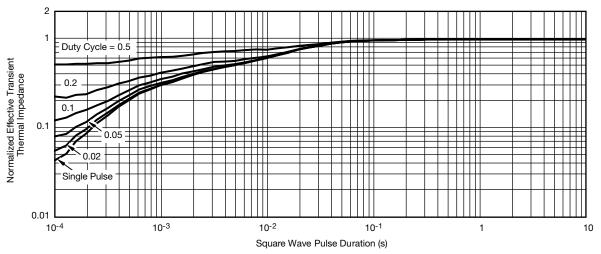
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

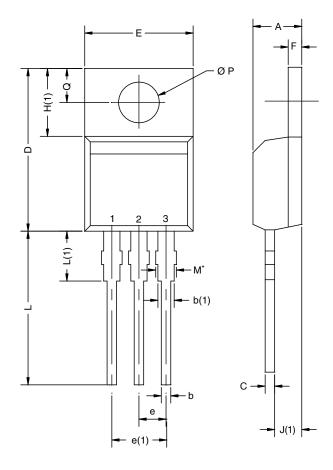
Note

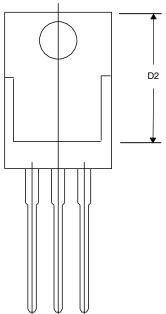
- The characteristics shown in the two graphs
- Normalized Transient Thermal Impedance Junction to Ambient (25 °C)
- Normalized Transient Thermal Impedance Junction to Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



TO-220AB





| | MILLIN | IETERS | INCHES | | |
|--|--------|--------|--------|-------|--|
| DIM. | MIN. | MAX. | MIN. | MAX. | |
| А | 4.25 | 4.65 | 0.167 | 0.183 | |
| b | 0.69 | 1.01 | 0.027 | 0.040 | |
| b(1) | 1.20 | 1.73 | 0.047 | 0.068 | |
| С | 0.36 | 0.61 | 0.014 | 0.024 | |
| D | 14.85 | 15.49 | 0.585 | 0.610 | |
| D2 | 12.19 | 12.70 | 0.480 | 0.500 | |
| Е | 10.04 | 10.51 | 0.395 | 0.414 | |
| е | 2.41 | 2.67 | 0.095 | 0.105 | |
| e(1) | 4.88 | 5.28 | 0.192 | 0.208 | |
| F | 1.14 | 1.40 | 0.045 | 0.055 | |
| H(1) | 6.09 | 6.48 | 0.240 | 0.255 | |
| J(1) | 2.41 | 2.92 | 0.095 | 0.115 | |
| L | 13.35 | 14.02 | 0.526 | 0.552 | |
| L(1) | 3.32 | 3.82 | 0.131 | 0.150 | |
| ØΡ | 3.54 | 3.94 | 0.139 | 0.155 | |
| Q | 2.60 | 3.00 | 0.102 | 0.118 | |
| ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471 | | | | | |

Note

 * M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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